505681942 09/20/2019

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5728750

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Shih-Min Chou	09/18/2019
Kuo-Chih Lai	09/18/2019
Wei-Ming Hsiao	09/18/2019
Hui-Ting Lin	09/18/2019
Szu-Yao Yu	09/18/2019
Nien-Ting Ho	09/18/2019
Hsin-Fu Huang	09/18/2019
Chin-Fu Lin	09/18/2019

RECEIVING PARTY DATA

Name:	UNITED MICROELECTRONICS CORP.	
Street Address:	No.3, Li-Hsin Road 2, Science-Based Industrial Park	
City:	Hsin-Chu City	
State/Country:	TAIWAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16576784

CORRESPONDENCE DATA

505681942

Fax Number: (703)997-4517

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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Correspondent Name: WINSTON HSU

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Address Line 4: NEW TAIPEI CITY, TAIWAN

ATTORNEY DOCKET NUMBER:	NAUP3494USA
NAME OF SUBMITTER:	KATE YEH
SIGNATURE:	/KATE YEH/
DATE SIGNED:	09/20/2019

PATENT REEL: 050439 FRAME: 0107

tal Attachments: 16
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PATENT REEL: 050439 FRAME: 0108

Title of Invention:

RERAM STRUCTURE AND METHOD OF FABRICATING THE SAME

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
☐ United States application nu	mber	_filed on	, or
☐ PCT international application	n number	filed on	
The above-identified application was	made or authorized to be made	by me.	
I believe that I am the original invent application.	or or an original joint inventor of a	a claimed invention in the	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or impr			
In consideration of the payment by	UNITED MICROELECTROI CORP.	NICS having a postal ad	dress of
No.3, Li-Hsin Road 2, Science	e-Based Industrial Park, Hs	in-Chu City 300, Taiwa	n, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good are		00), the receipt of which is h	ereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application o substitutes, or extensions thereof, an	nd to any and all improvements w ution and, in and to, all Letters Pat r any continuations, continuation-	which are disclosed in the tent to be obtained for said in-part, divisions, renewals,	
I hereby covenant that no assignme entered into which would conflict wit		nce has been or will be mad	e or
I further covenant that ASSIGNEE wand documents relating to said inverknown and accessible to I and will to related thereto and will promptly exercise.	ntion and said Letters Patent and estify as to the same in any interfe	legal equivalents as may be erence, litigation proceeding	9
representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention and said lecessary or desirable to carry out	Letters Patent and said the proposes thereof.	
Note: An application data sheet (PT inventive entity, must accompany the	O/SB/14 or equivalent), including is form. Use this form for each ad	naming the entire ditional inventor.	

Page 1 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)		
Inventor:	Shih-Min Chou	Date:	SEP 1 8 2019
Signature:	Shih-Min Chou		

Page 2 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

Title of Invention:

Reram Structure and Method of Fabricating the Same

As the below named inventor, I herel This declaration is directed to:	by declare that:		
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☐ United States application nu	mber	filed on	, or
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I believe that I am the original inventor application.	or or an original joint inventor of a	claimed invention in the	
I hereby acknowledge that any willful under18 U.S.C. 1001 by fine or impri	false statement made in this dec sonment of not more than five (5)	elaration is punishable gyears, or both.	
In consideration of the payment by	UNITED MICROELECTRON	IICS having a postal add	iress of
No.3, Li-Hsin Road 2, Science	-Based Industrial Park, Hsi	n-Chu City 300, Taiwan	ı, R.O.C
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an		0), the receipt of which is he	reby
I hereby sell, assign and transfer to A the entire right, title and interest in an invention as above-identified application or substitutes, or extensions thereof, an	nd to any and all improvements w tion and, in and to, all Letters Pat any continuations, continuation-i	hich are disclosed in the ent to be obtained for said n-part, divisions, renewals,	IEE
I hereby covenant that no assignmer entered into which would conflict with		ce has been or will be made	or
I further covenant that ASSIGNEE w and documents relating to said inven- known and accessible to I and will te related thereto and will promptly exe-	ition and said Letters Patent and stify as to the same in any interfe	legal equivalents as may be rence, litigation proceeding	ots
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be ne IN WITNESS WHEREOF, I have her	olication, said invention and said L cessary or desirable to carry out	etters Patent and said. the proposes thereof.	
Note: An application data sheet (PTC inventive entity, must accompany thi			

Page 3 of 16

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Kuo-Chih Lai Date: SEP 1 8 2019

Signature: Kw-Click Lai

Page 4 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

Title of Invention:

Reram Structure and Method of Fabricating the Same

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No.3, Li-Hsin Road 2, Science	-Based Industrial	Park, Hsin-Chi	u City 300, T	aiwan, R.O.C.
(referred to as "ASSIGNEE"below) to acknowledged, andfor other good an			receipt of whic	ch is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in an invention as above-identified applica invention by the above application of substitutes, or extensions thereof, ar	nd to any and all impro tion and, in and to, all rany continuations, co	vements which a Letters Patent to l ntinuation-in-part,	re disclosed in be obtained for divisions, rene	the said wals,
I hereby covenant that no assignment entered into which would conflict with		encumbrance has	been or will be	e made or
I further covenant that ASSIGNEE w and documents relating to said inver known and accessible to I and will te related thereto and will promptly exe	ntion and said Letters I estify as to the same in	Patent and legal e any interference,	quivalents as n litigation proce	nay be
representatives any and all papers, i maintain, issue and enforce said app equivalents thereof which may be no IN WITNESS WHEREOF, I have her	olication, said invention ecessary or desirable t	n and said Letters o carry out the pro	Patent and sai poses thereof.	
Note: An application data sheet (PTC inventive entity, must accompany this				

Page 5 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

Inventor: Wei-Ming Hsiao Date: SEP 1 8 2019

Signature: Wei-Ming Hsiao

Page 6 of 16

Title of Invention:

Reram Structure and Method of Fabricating the Same

As the below named inventor, I here This declaration is directed to:	by declare that:		
☑ The attached application, or			
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(referred to as "ASSIGNEE"below) to acknowledged, andfor other good ar	o I of the sum of One Dollar (\$ 1. nd valuable consideration.	00), the receipt of which i	is hereby
I hereby sell, assign and transfer to a the entire right, title and interest in a invention as above-identified applica- invention by the above application of substitutes, or extensions thereof, an	nd to any and all improvements vition and, in and to, all Letters Par r any continuations, continuation	which are disclosed in the itent to be obtained for sa -in-part, divisions, renewa	e aid als,
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Page 7 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Hui-Ting Lin		Date:	SEP 1 8 2019
Signature:	Hui-Ting	īh		

Page 8 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

Title of Invention:

Reram Structure and Method of Fabricating the Same

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(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.					
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.					
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;					
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal					
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.					
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor					

Page 9 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Szu-Yao Yu Date: SEP 1 8 2019

Signature: SZU-YAO YU

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NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

Title of Invention:

Reram Structure and Method of Fabricating the Same

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representatives any and all papers, maintain, issue and enforce said appequivalents thereof which may be no IN WITNESS WHEREOF, I have he	plication, said invention ecessary or desirable	on and said Letters to carry out the pr	s Patent and sai roposes thereof.	
Note: An application data sheet (PT				

Page 11 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

LEGAL NAME OF INVENTOR(ASSIGNOR)				
Inventor:	Nien-Ting Ho	Date:	SEP 1 8 2019	
Signature:	Nien-Ting Ho.	The second secon		

Page 12 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

Title of Invention:

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Page 13 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

LEGAL NAI	ME OF INVENTOR(ASSIGNOR)		
Inventor:	Hsin-Fu Huang	Date:	SEP 1 8 2019
Signature:	Hisin-Fy Huang		

Page 14 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

Title of Invention:

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Page 15 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Chin-Fu Lin

Date:

SEP 1 8 2019

Signature:

Chin-Fa lou

Page 16 of 16

NPO#NAU-P3494-USA:0 CUST#UMCD-2019-0299

RECORDED: 09/20/2019

F#NPO-P0002E-US1201 DSB0-108U020159

PATENT REEL: 050439 FRAME: 0124